

DIXTRA ELECTRONIC 99Sn0,3Ag0,7Cu (SAC 0307)

FEATURES

- Cost effective
- Fast soldering and good wettability
- Reliable joints
- Low dross production
- Excellent wetting speed
- Compatibility with all fluxes
- Low soldering defects
- Low copper dissolution rate

DESCRIPTION

. The alloy 99Sn0,3Ag0,Cu has been formulated as a cheap alternative to the traditional SAC alloys and as an effective drop in to the Sn/Cu cheap alloys.

In wave soldering, 99Sn0,3Ag0,7Cu offers a superior wetting if compared to the others SnCu alloys. Dross production is low, mechanical strength is optimal and wettability is very good.

Copper dissolution rate is lower than Sn/Cu .

IMPURITIES LEVELS ACCORDING THE MAIN NORMS

NORM	Sn	Pb	Sb	Bi	Cd	Cu	In	Ag	Al	As	Fe	Zn	Ni
ISO 9453:2014 (E)	Resto	0,07	0,10	0,10	0,002	0,5-0,9	0,10	0,2-0,4	0,001	0,03	0,02	0,001	0,01
IPC- JSTD 006	Resto	0,10	0,50	0,10	0,002	0,5-0,9	0,10	0,2-0,4	0,005	0,03	0,02	0,003	0,01

COMPATIBILITY WITH FLUXES

La 99Sn0,3Ag0,7Cu bar solder is compatible with all major brands of no-clean and water soluble electronic grade fluxes

TEMPERATURE REQUIREMENTS

Melting temperature : 227°-230°C

Pot temperature : 265 – 275°C

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.